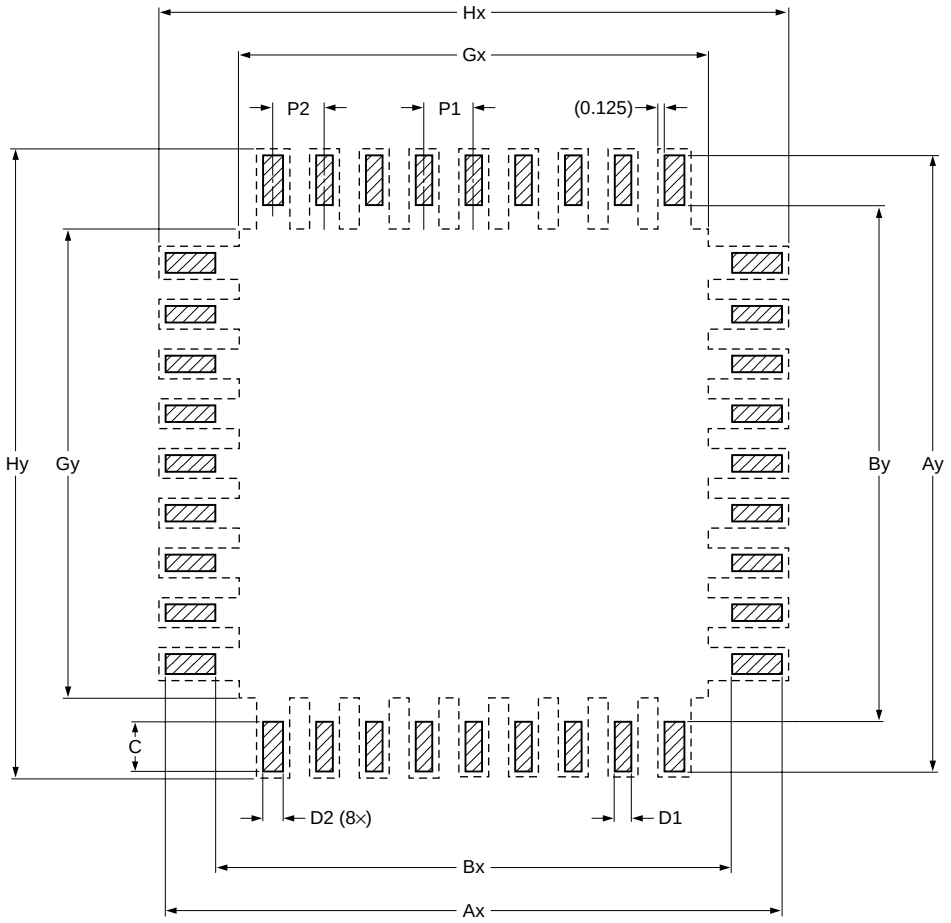
Footprint information for reflow soldering of QFP128 package **SOT320-3**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.800	0.850	33.300	33.300	28.900	28.900	2.200	0.500	0.600	28.500	28.500	33.550	33.550

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